PCN Number:	20190807005.1	**PCN Date:**	Aug 15 2019
Title:	Qualification of new Mold Compound for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Nov 15 2019	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

This PCN is to inform of a new mold compound qualification for the devices in the product affected section below as follows:

Current Mold Compound	New Mold Compound
SID#101323701	**SID#101355509**

Reason for Change:

Current mold compound is being discontinued

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

None

Product Affected:

TLK2226GEA	TMS32C6211BZFNA150	TNETV2010AFNBZDS	TNETV2021AFIDWZDS
TMS320C6211BGFN150	TNETV1051DACLZDW	TNETV2010AZDS	TNETV2021AGDS
TMS320C6211BZFN150	TNETV1051EACLZDW	TNETV2020AVNDZDS	TNETV2021AVISWGDS
TMS320C6211BZFN167	TNETV1052ACLZDW	TNETV2020AZDS	TNETV2021AZDS
TMS32C6211BGFNA150	TNETV1053ZDW	TNETV2021ACLZDS	

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TNETV1051EACLZDW	Qual Device: TNETV2020AZDS
PC	Preconditioning	Level 3 - 260C	-	3/461/0 [1]
PC	Preconditioning	Level 4 - 260C	3/462/0	-
TC	Temperature Cycle, -55C/125C	700 Cycles	3/231/0	3/229/0 [2]
TC-WBP	Auto Post TC Bond Pull	Post Temperature Cycle	3/90/0	3/90/0
UHAST	Unbiased HAST, 110C	264 Hours	3/231/0	3/230/0 [3]
MQ	Manufacturability (Assembly)	(per mfg. site requirements)	3/Pass	3/Pass
VM	Visual Quality Reliability Inspection	Post Temperature Cycle	3/6/0	3/6/0
XRAY	X-ray	top side only	3/15/0	3/15/0
YLD	FTY and Bin Summary	-	2/Pass	3/Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Notes:
1. One unit failed for PLL functional test post preconditioning – not related to assembly, package or mold compound change – discounted.
2. Two units failed. One failure is the post preconditioning PLL functional test failure – not related to assembly, package or mold compound change – discounted. Second failure was for open due to missing solder ball caused by indexer issue – not related to assembly, package or mold compound change – discounted.
3. One unit failed for open due to missing/damaged solder balls caused by device handling issue – not related to assembly, package or mold compound change – discounted.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property

right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.